

Amendments to the Claims:

Claims 1-36 (Cancelled).

37. (New) A thermally conductive substrate comprising:

a thermally conductive resin sheet member formed of a thermosetting resin mixture, said thermosetting resin mixture including 70 to 90 parts by weight of an inorganic filler and 5 to 30 parts by weight of a thermosetting resin composition comprising a thermosetting resin in a semi-cured state; and

a lead frame integrated with said thermally conductive resin sheet member.

38. (New) The thermally conductive substrate of claim 37, wherein said thermally conductive resin sheet member has a gel time in a range between 20 seconds and 120 seconds at a temperature of 155 °C.

39. (New) The thermally conductive substrate of claim 38, wherein said thermally conductive resin sheet member has a viscosity in a range between 102 Pa.s and 105 Pa.s.

40. (New) The thermally conductive substrate of claim 38, wherein said lead frame includes a through-opening, said through-opening being filled with said thermally conductive resin sheet member so that said thermally conductive resin sheet member and said lead frame are integrated to form a flush surface.

41. (New) The thermally conductive substrate of claim 38, wherein said thermosetting resin composition includes at least one component selected from a group consisting of a bisphenol A epoxy resin, a bisphenol F epoxy resin, and a liquid phenol resin.

42. (New) The thermally conductive substrate of claim 38, wherein said inorganic filler comprises at least one material selected from a group consisting of Al_2O_3 , MgO, BN and AlN.

43. (New) The thermally conductive substrate of claim 38, wherein said thermally conductive resin sheet member is integrated with a portion of said lead frame, said lead frame including an outer frame portion connected to a common terminal, and including a second terminal electrically connected to said outer frame portion through said common terminal.

44. (New) The thermally conductive substrate of claim 38, wherein said lead frame is located on a first side of said thermally conductive resin sheet member, said thermally conductive resin sheet member including at least one terminal on said first side, said at least one terminal being electrically independent of said lead frame.

45. (New) The thermally conductive substrate of claim 37, wherein said thermally conductive resin sheet member has a viscosity in a range between 102 Pa.s and 105 Pa.s.

46. (New) The thermally conductive substrate of claim 37, wherein said lead frame includes a through-opening, said through-opening being filled with said thermally conductive resin sheet member so that said thermally conductive resin sheet member and said lead frame are integrated to form a flush surface.

47. (New) The thermally conductive substrate of claim 37, wherein said thermosetting resin composition includes at least one component selected from a group consisting of a bisphenol A epoxy resin, a bisphenol F epoxy resin, and a liquid phenol resin.

48. (New) The thermally conductive substrate of claim 37, wherein said inorganic filler comprises at least one material selected from a group consisting of Al_2O_3 , MgO, BN and AlN.

49. (New) The thermally conductive substrate of claim 37, wherein said thermally conductive resin sheet member is integrated with a portion of said lead frame, said lead frame including an outer frame portion connected to a common terminal, and including a second terminal electrically connected to said outer frame portion through said common terminal.

50. (New) The thermally conductive substrate of claim 37, wherein said lead frame is located on a first side of said thermally conductive resin sheet member, said thermally conductive resin sheet member including at least one terminal on said first side, said at least one terminal being electrically independent of said lead frame.